
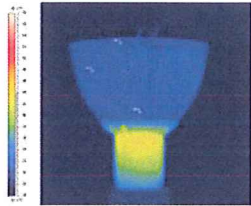
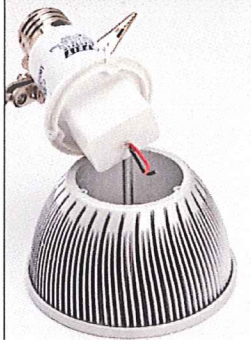

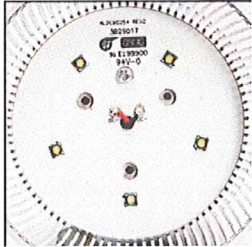
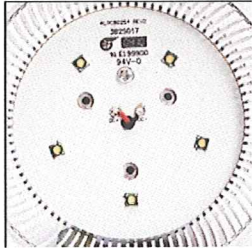
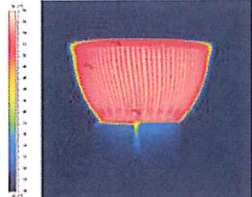


EXHIBIT C

Feit Electric Company, Inc.
 Product: PAR30/L/HP/LED
 Patent: U.S. Patent No. 6,787,999

| Claim | PAR30/L/HP/LED |
|---|--|
| <u>Claim 8</u> | |
| A light emitting apparatus comprising: | |
| a heat sink having a first side, a second side opposite the first side, and conduit connecting the first side and the second side; | <div data-bbox="867 554 1117 806" data-label="Image"> </div> <div data-bbox="867 835 1117 1058" data-label="Image"> </div> <div data-bbox="1133 554 1409 617" data-label="Text"> <p>a heat sink having a first side</p> </div> <div data-bbox="1133 898 1409 1016" data-label="Text"> <p>a second side opposite the first side, and conduit connecting the first side and the second side</p> </div> |
| a plurality of light emitting diodes disposed at the first side of the heat sink and in thermal communication therewith to heat sink the light emitting diodes; | <div data-bbox="867 1087 1117 1339" data-label="Image"> </div> <div data-bbox="867 1365 1117 1562" data-label="Image"> </div> <div data-bbox="1133 1087 1409 1184" data-label="Text"> <p>plurality of light emitting diodes disposed at the first side of the heat sink</p> </div> <div data-bbox="1133 1402 1409 1520" data-label="Text"> <p>and in thermal communication therewith to heat sink the light emitting diodes</p> </div> |

| <u>Claim</u> | <u>PAR30/L/HP/LED</u> | |
|--|---|--|
| and an electronic module disposed at the second side of the heat sink and in thermal communication therewith to heat sink the electronic module, |   | <p>electronic module disposed at the second side of the heat sink</p> <p>and in thermal communication therewith to heat sink the electronic module</p> |
| the electronic module converting electrical input power into a conditioned electrical power, |  | <p>electronic module converting electrical input power into a conditioned electrical power</p> |
| the light emitting diodes receiving the conditioned electrical power from the electronic module via the conduit. |  | <p>light emitting diodes receiving the conditioned electrical power from the electronic module via the conduit</p> |

| <u>Claim</u> | <u>PAR30/L/HP/LED</u> |
|--|---|
| <u>Claim 9</u> | |
| The light emitting apparatus as set forth in claim 8, further including: | |
| a PC board in which the plurality of light emitting diodes are arranged, |  <p data-bbox="1133 443 1409 537">PC board in which the plurality of light emitting diodes are arranged</p> |
| the pc board disposed at the first side of the heat sink and in thermal communication therewith. |   <p data-bbox="1133 720 1409 783">PC board disposed at the first side of the heat sink</p> <p data-bbox="1133 997 1409 1087">and in thermal communication therewith</p> |

